

MANUFACTURE OF SEMICONDUCTOR DEVICE

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Abstract

PROBLEM TO BE SOLVED: To prevent ICs from deteriorating in manufacturing yield by a method wherein spin-on liquid is applied onto a wafer, and then a coating film is removed from the circumference of the wafer keeping the wafer rotating, the wafer is made to stop rotating and tilted, edge rinsing liquid is dropped down along the OF of the wafer, and the coating film is removed from the OF of the wafer.

SOLUTION: Spin-on liquid is dropped down from a nozzle 4 on the upper center of a wafer 3 fixed in a horizontal position on a spin chuck 2, the spin chuck 2 is rotated at a high speed to form a coating film 5. Then, edge rinsing liquid is dropped down on the peripheral part of the wafer from a nozzle 6 to remove a coating film from the periphery of the wafer 3 as the spin chuck 2 is rotated at a low speed. Then, the wafer 3 is made to stop rotating, the OF of the wafer 3 is set at a prescribed position, and the spin chuck 2 is tilted by an angle of 30 to 50 degrees with a tilting motor 8. Then, the nozzle 6 is made to approach a point above the OF of the wafer 3, and edge rinsing liquid is dropped down from the nozzle 6 to remove a coating film from the OF of the wafer 3 as the nozzle 6 is moved along the OF of the wafer 3.

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